



The European Electronics Association

***"The Future Needs of the Global Electronics Industry.
What Solutions will Europe Provide?"***



EIPC Winter Conference 2017

Date: February 2 & 3, 2017

Location: Wyndham Grand Hotel Salzburg
Salzburg, Austria

Bonus Programme: Visit Hangar 7;

Historical Flying Bulls aircraft fleet and Formula 1 race cars

Please note: numbers of visitors for the bonus programme are limited, on a first-come, first-served basis, so make sure you are one of the first.

Day 1: 08:30-22:30 hrs.

- Welcome by EIPC Chairman, Alun Morgan
- Keynote Speech
- Session 1: New system designs and impact on material & processes
- Networking Lunch
- Session 2: Advanced Component and Attachment technologies for High First Pass Yields
- Session 3: Developments in Soldering and Solderable Finishes
- Bonus programme: Visit Hangar 7
- Networking dinner at Restaurant M32

Day 2: 09:00-14:15 hrs.

- Session 4: Future Electronic Application and Impact on Reliability and Safety
- Session 5: Reliability of PCBAs and PCBs
- Networking Lunch

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World Electronic Circuits Council

The EIPC is the European representative at the WECC



Institute of Circuit Technology
www.instct.org



Fachverband für Design, Leiterplatten- und Elektronikfertigung



Maskless Electrochemical Surface Modification Process
www.mesmoproc.eu

*Please visit
www.eipc.org
for the latest news*

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EIPC Winter Conference Salzburg, Austria, February 2 & 3, 2017

“Future Needs of the Global Electronics Industry. What Solutions will Europe Provide?”

Programme

The European Electronics Association is extending an invitation to companies and individuals active in the Packaging and Interconnection Industry to participate in the EIPC Winter Conference to be held on February 2 & 3, 2017 in Salzburg, Austria. The aim of the Conference is to provide a platform for speakers and delegates to exchange information on market conditions and future innovation on interconnection and packaging.

Delegates and visitors from throughout Europe will attend this event, offering presenters the opportunity to reach a targeted audience of decision makers and leaders of the international packaging and interconnection industry. This conference is an absolute ‘must’ for companies associated with PCB fabrication who wish to stay up to date with the latest market requirements, materials, fabrication equipment and manufacturing processes who also need to improve the efficiency of their processes and the reliability of their products.

Who should attend?

Engineers and decision-makers in the field of OEMs, EMS, assembly, and PCB fabricators as well as board and system designers at all levels are invited to participate. Circuit board designers, looking into more cost-effective solutions and miniaturisation, will learn about the developing trends in different applications. Board fabricators and development engineers will gain background information that will help to focus on more profitable products. Specialists and marketing managers will gain additional background data to focus on advanced PCB applications. OEMs will get a better understanding on how to get prepared for the next generation of electronic products.

Detailed information about the conference hotel

EIPC has chosen the Wyndham Grand Hotel Salzburg. The hotel is located in the city centre, 500m from the main station, 5km from the Salzburg airport.

EIPC has negotiated a special rate for a single room of € 124.- per night, including breakfast.

You can reserve your hotel room directly at the hotel by contacting the hotel at +43-662 4688 0 or info@wyndhamgrandsalzburg.com, please use the keywords ‘EIPC SALZBURG’. Reservations can be made until January 16, 2017. After this release date availability is on request.

Wyndham Grand Salzburg Hotel
Fanny-von-Lehnert Strasse 7
5020 Salzburg, Austria
Tel: +43-662 46880
www.wyndhamgrandsalzburg.com

Bonus Programme

On Thursday February 2, we will visit the Red Bull Hangar 7. We will go by coach from the conference hotel to Hangar 7. Hangar-7 at Salzburg Airport is a unique building which houses the historical Flying Bulls aircraft fleet and a collection of Formula 1 race cars. Hangar-7 also offers space for art exhibitions. More information is available on www.hangar-7.com

Networking Event

In the evening we will be having dinner all together at the excellent Restaurant M32. An opportunity to chat, gossip, enjoy good food and wine, and maybe learn something one didn’t know. As usual, this will be a convivial and sociable event open to conference delegates and their guests.

Table top exhibition and poster display area

During the Conference the EIPC will provide an opportunity for information sharing and discussion in a dedicated area. This will allow visitors to obtain latest product information and know how on an informal, or ‘one-to-one’ basis. A ‘poster wall’ and a table will be provided during the two days of the conference. If you are interested please download the registration form at www.eipc.org.

Conference Sponsoring

The EIPC offers several possibilities for sponsoring the EIPC Winter Conference Salzburg 2017. You can download the various possibilities that could be a great asset to your company’s exposure on the EIPC website or contact the EIPC office at kwestenberg@eipc.org

Sponsor of the EIPC Winter Conference Salzburg:



Press sponsors:



Conference Programme Day 1, Thursday February 2

Conference Registration and Table Top & Poster Exhibition build up	Table Top & Poster Display Area
Welcome by the EIPC Chairman	Alun Morgan, EIPC, UK
Keynote Speech - Business Outlook Global Electronics Industry	Walt Custer, Custer Consulting, USA
Q & A	
Session 1: New system designs and impact on material & processes	Moderator: Alun Morgan, EIPC, UK
Systems design – Moore's law and semiconductor industry changes, their effect and influences on PCB design	Nikola Kontic, Zuken, UK
Influences of laminate and PCB Manufacturing tolerances on patch antenna and feed network characteristics	Alexander Ippich, Isola, DE
Coffee break	
PCB Technology Requirements for Millimeter-Wave Interconnect and Antenna	Jim Francey, Optiprint, UK
Ultra High Density Interconnect Printed Circuit Boards	Karl-Heinz Fritz, Cicor, CH
EMC conformal board design	Prof. Rainer Thüringer (Chairman FED) , TH-Mittelhessen, DE
Panel discussion	
Networking Lunch	Hotel Restaurant
Session 2: Advanced Component and Attachment technologies for High First Pass Yields	Moderator: Christian Behrendt, Ilfa, DE
Component trends, surface finishes trends and what is expected of first pass yield and what support is needed from suppliers in the industry	TBA
Sinter paste for NiAu PCB Substrate with a pressure-less and low temperature process	Wolfgang Schmitt, Heraeus Electronics, DE
Future electrical property needs drive Semi Additive Processes into high volume PCB manufacturing	Uwe Altmann, Orbotech SA, BE
Registration, improving yield and reducing costs of the PCB manufacturing process	Stephan Kunz, Schmoll Maschinen, DE
Panel discussion	
Coffee break	
Session 3: Developments in Soldering and Solderable Finishes	Moderator: Martyn Gaudion, Polar Instruments, UK
Reliability study of No Clean Chemistries for Lead Free solder paste in Vapour phase reflow	Emmanuelle Guene, Inventec, FR
Optimization of chemistry for a vapour phase process for defluxing No Clean lead free materials	Patrick Duchi, Inventec, CH
Manufacturing Advanced Coatings for Future Electronic Systems (MACFEST)	Prof. Karl Ryder, University of Leicester, UK
Panel discussion	
Departure & Tour Red Bull Hangar 7	
Dinner @ Restaurant M32	
Return to Hotel	

*The EIPC is not responsible for the content and the presentation of the technical papers, which rests with the presenters.
Changes in the programme may occur, due to circumstances, for which the EIPC may not be held responsible.*



Conference Programme Day 2, Friday February 3

Session 4: Future Electronic Application and Impact on Reliability and Safety	Moderator: Pete Starkey, Iconnect007, UK
Welcome day 2 by Session Chairman	
Keynote Speech- PCB material toolbox for todays 3 and 4G networks and future 5G compliance	Stig Källman, Ericsson, SE
Recognition in the view of a PCB manufacturer	Jürgen Deutschmann, AT&S, AT
UL PCB Recognition: A 20 minute guide to the UL 796 safety standard	Emma Hudson, UL, UK
Heat spreading Mask / Mask for Direct Imaging	Don Monn, Taiyo, USA
Panel Discussion	
30 minutes Coffee break	Table Top & Poster Display Area
Session 5: Reliability of PCBAs and PCBs	Moderator: Michael Weinhold, EIPC, DE
Nondestructive Failure Analysis — Image and Reality. Matching findings (facts) with expectations (theories). Or not. Case studies from the coalface	Robert Mr. Boguski, Datest, USA
Efficient test methods for prototype builds and small batch production in electronics assembly	Hermann Reischer, Polar Instruments, DE
Tolerance requirements	TBA, Ilfa Feinstleiter Technologie, DE
Panel Discussion	
Chairman closing remarks - End of conference day 2	
Networking Lunch	Hotel Restaurant

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